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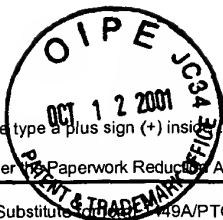
Substitute for Form 1449A/PT INFORMATION DISCLOSURE STATEMENT BY APPLICANT (use as many sheets as necessary)		Complete if Known	
		Application Number	09/773,522
		Filing Date	February 20, 2001
		First Named Inventor	Paul A. Farrar
		Group Art Unit	N/A
		Examiner Name	Not Yet Assigned
Sheet	2	of	2
		Attorney Docket Number	M4065.0392/P392

OTHER PRIOR ART – NON PATENT LITERATURE DOCUMENTS			
Examiner Initials	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
	L	Solder Transfer Technique for Flip-Chip and Electronic Assembly Applications, Karl J. Puttlitz, et al., IEEE Transactions on Components, Packaging and Manufacturing Technology, Part C, Vol. 21, No. 3, July, 1998.	
	M	MicroJet Printing of Solder and Polymers for Multi-Chip Modules and Chip-Scale Packages, Donald J. Hayes et al., MicroFab Technologies, Inc., IMPAS '99.	
	N	Self-Aligned Controlled Collapse Chip Connect (SAC4), L. Pfeiffer et al., J. Electrochem. Soc.: Solid-State Science and Technology, November 1987.	
	O	Review of Flip Chip Bonding, Vincent C. Marcotte, et al., IBM East Fishkill Facility.	
	P	Solder Jet Printing of Micropads and Vertical Interconnects, David B. Wallace, et al., www.microfab.com/paper/smta97/smta97.htm, (8/12/00).	
	Q	Combination Process for Final Metal Lines and Metal Terminals, Research Disclosure, No. 34232, Kenneth Mason Publications Ltd., England (October 1992/753).	
	R	Process for High Density of Chip Terminals on Large Wafers, Research Disclosure, 34625 Kenneth Mason Publications Ltd., England (February 1993/97).	
	S	Key Process Controls for Underfilling Flip Chips, Alec J. Babiarz et al., Solid State Technology, 1997 by PennWell Publishing Company.	
	T	Mark's Standard Handbook for Mechanical Engineers, Tenth Edition, Eugene A. Avallone, et al.	
	U	Flow of gases through tubes and orifices, David G. Worden, Scientific Foundations of Vacuum Technique, Saul Dushman.	
	V	Sorption of gases by "active" charcoal, silicates (including glasses), and cellulose, "Scientific Foundations of Vacuum Technique", J. Wiley and Sons (1962).	
	W	Electronic Materials Handbook, Vol. 1, Packaging, pages 301, 440.	
	X	Technology Challenges for Advanced Interconnects, James G. Ryan et al, Conference Proceedings ULSI XIII©1998 Materials Research Study.	

Examiner Signature	B. Talbot	Date Considered	3/28/03
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U.S. PATENT DOCUMENTS						
Examiner Initials*	Cite No. ¹	U.S. Patent Document		Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document MM-DD-YYYY	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number	Kind Code ² (if known)			
BT	A	6,074,895		Dery et al.	06/13/00	
	B	6,117,299		Rinne et al.	09/12/00	
	C	3,959,047		Alberts et al.	05/25/76	
	D	5,240,878		Fitzsimmons et al.	08/31/93	
	E	5,693,572		Bond et al.	12/02/97	
	F	5,642,261		Bond et al.	06/24/97	
	G	5,461,257		Hundt	10/24/95	
	H	5,457,345		Cook et al.	10/10/95	
	I	6,133,634		Joshi	10/17/00	
	J	4,532,530		Hawkins	07/30/85	
BT	K	6,122,177		Kitano et al.	09/19/00	

FOREIGN PATENT DOCUMENTS								
Examiner Initials*	Cite No. ¹	Foreign Patent Document			Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document MM-DD-YYYY	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T ⁶
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Examiner Signature	B Talbot	Date Considered	3/28/03
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